

ABSTRACT OF THE DISCLOSURE

To provide a low-cost semiconductor device that obtains a reduction in pitch and an increase in the number of pins using conventional equipment and to provide a method of manufacturing the semiconductor device. The semiconductor device according to the present invention includes: a flexible printed circuit, on which a semiconductor chip is mounted, having a connection terminal portion that includes a plurality of land-shaped connection terminals arranged in a step form or a grid form and an insulating film provided to a conductor connected with the respective land-shaped connection terminals. Further, a method of manufacturing a semiconductor device according to the present invention includes: forming a flexible printed circuit including a connection terminal portion in which a plurality of land-shaped connection terminals are arranged in a step form or a grid form and an insulating film is provided to a conductor connected with the respective land-shaped connection terminals; mounting a semiconductor chip on the flexible printed circuit; and separating a semiconductor device from the flexible printed circuit by cutting a portion of each of outermost land-shaped connection terminals.